

Citations to Tsai (2011)

Source Document

Tsai, M. Y., & Chen, W. K. (2011, July). Effect of CMP conditioner diamond shape on pad topography and oxide wafer performances. *The International Journal of Advanced Manufacturing Technology*, 55, 253-262.

Citations: June 2012 – December 2013 (in chronological order)

Zhong, Z. W., Tian, Y. B., Ang, Y. J., & Wu, H. (2012, June). Optimization of the chemical mechanical polishing process for optical silicon substrates. *The International Journal of Advanced Manufacturing Technology*, 60, 1197-1206.

Wang, T., Zhao, D., He, Y., & Lu, X. (2013, August). Effect of slurry injection position on material removal in chemical mechanical planarization. *The International Journal of Advanced Manufacturing Technology*, 67, 2903-2908.

Tian, Y. B., Zhong, Z. W., Lai, S. T., & Ang, Y. J. (2013, September). Development of fixed abrasive chemical mechanical polishing process for glass disk substrates. *The International Journal of Advanced Manufacturing Technology*, 68, 993-1000.

Kwon, T. Y., Ramachandran, M., Cho, B. J., Busnaina, A. A., & Park, J. G. (2013, November). The impact of diamond conditioners on scratch formation during chemical mechanical planarization (CMP) of silicon dioxide. *Tribology International*, 67, 272-277.

Kwon, T. Y., Ramachandran, M., & Park, J. G. (2013, December). Scratch formation and its mechanism in chemical mechanical planarization (CMP). *Friction*, 1, 279-305.